PCN Number:	20181022004.0	PCN Date	Ctober	24, 2018
Title: Datasheet for	or TMP303			
Customer Contact:	PCN Manager		Dept:	Quality Services
Change Type:				
Assembly Site	Desig	gn	N	/afer Bump Site
Assembly Process		Sheet		lafer Bump Material
Assembly Materia		number change		lafer Bump Process
Mechanical Specif				lafer Fab Site
Packing/Shipping	/Labeling Test	Process		lafer Fab Materials
				lafer Fab Process
		cation Detai	S	
Description of Chan				
The product datasheet	corporated is announci t(s) is being updated a history provides furthe	s summarized b		cation.
TEXAS INSTRUMENTS			SBOS486H	TMP303 -JULY 2009-REVISED OCTOBER 2018
Changes from Revision G ((July 2017) to Revision H			Page
Changed supply voltage	maximum value in the Absol	ute Maximum Rating	s table from: 3.0	5 V to: 4 V
· Changed input pin voltag	e maximum value in the Abs	olute Maximum Rati	ngs table from: '	
 Changed output pin volta 	ge maximum value n the Ab	solute Maximum Rat	ings table from:	
 Updated junction-to-ambi 	ient thermal resistance from	168 °C/W to 210.3 °C	C/W	5
 Updated junction-to-case 	(to a) the second second second from			
- opualeu junction-to-case	(top) thermal resistance from	n 2.4 °C/W to 105.0	°C/W	
 Updated junction-to-board Updated junction-to-top of 	d thermal resistance from 42 characterization parameter fro	.3 °C/W to 87.5 °C/V om 0.9 °C/W to 6.1 °	v c/w	
 Updated junction-to-board Updated junction-to-top of 	d thermal resistance from 42 characterization parameter fro	.3 °C/W to 87.5 °C/V om 0.9 °C/W to 6.1 °	v c/w	5
 Updated junction-to-boar Updated junction-to-top c Updated junction-to-board 	d thermal resistance from 42 characterization parameter fro d characterization parameter	.3 °C/W to 87.5 °C/V om 0.9 °C/W to 6.1 °	v c/w	
Updated junction-to-board Updated junction-to-top of Updated junction-to-board <u>The datasheet number</u>	d thermal resistance from 42 characterization parameter fro d characterization parameter	.3 °C/W to 87.5 °C/V om 0.9 °C/W to 6.1 ° from 42.3 °C/W to 8	V C/W 7.0 °C/W	5
 Updated junction-to-boar Updated junction-to-top c Updated junction-to-board 	d thermal resistance from 42 characterization parameter fro d characterization parameter	.3 °C/W to 87.5 °C/V om 0.9 °C/W to 6.1 ° from 42.3 °C/W to 8 Chan	v CW 7.0 °C/W ge From:	5 5 Change To:
Updated junction-to-board Updated junction-to-top of Updated junction-to-board The datasheet number Device Family TMP303	d thermal resistance from 42 characterization parameter fro d characterization parameter r will be changing.	.3 °C/W to 87.5 °C/V om 0.9 °C/W to 6.1 ° from 42.3 °C/W to 8 Chan SBOS	v CW 7.0 °CW ge From: 486G	5
Updated junction-to-board Updated junction-to-top of Updated junction-to-board The datasheet number Device Family TMP303	d thermal resistance from 42 characterization parameter fro d characterization parameter	.3 °C/W to 87.5 °C/V om 0.9 °C/W to 6.1 ° from 42.3 °C/W to 8 Chan SBOS	v CW 7.0 °CW ge From: 486G	5 5 Change To:
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 Updated junction-to-boar Updated junction-to-top of Updated junction-to-boar The datasheet number Device Family TMP303 These changes may be http://www.ti.com/prod Reason for Change: To accurately reflect de Anticipated impact No anticipated impact the actual device. Changes to product None. Product Affected: TMP303ADRLR TMP303CDRLR 	d thermal resistance from 42 characterization parameter from d characterization parameter r will be changing. e reviewed at the datast oduct/TMP303 levice characteristics. on Fit, Form, Function . This is a specification identification result TMP303ADRLT TMP303CDRLT	3 °C/W to 87.5 °C/W om 0.9 °C/W to 6.1 ° from 42.3 °C/W to 8 SBOS sheet links provi on, Quality or F change announ ing from this F TMP303BD TMP303DD	Zeliability (cm: 7.0 °C/W 486G ded. Zeliability (cement only PCN: RLR RLR RLR	5 Change To: SBOS486H positive / negative): There are no changes to
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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